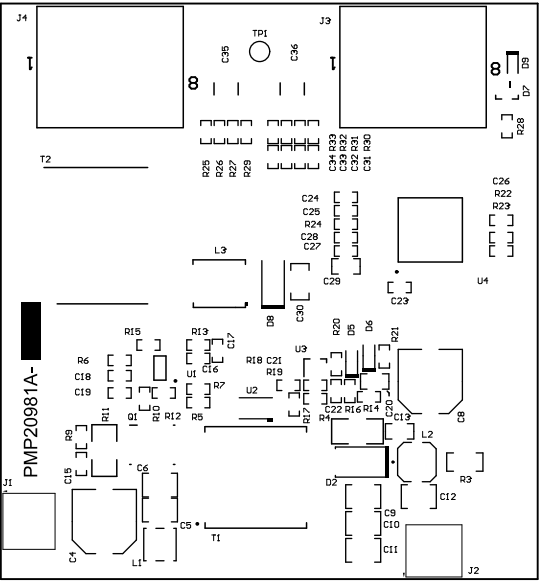
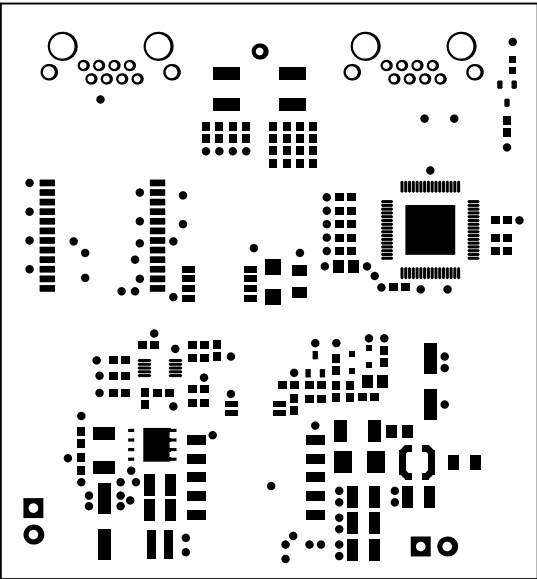
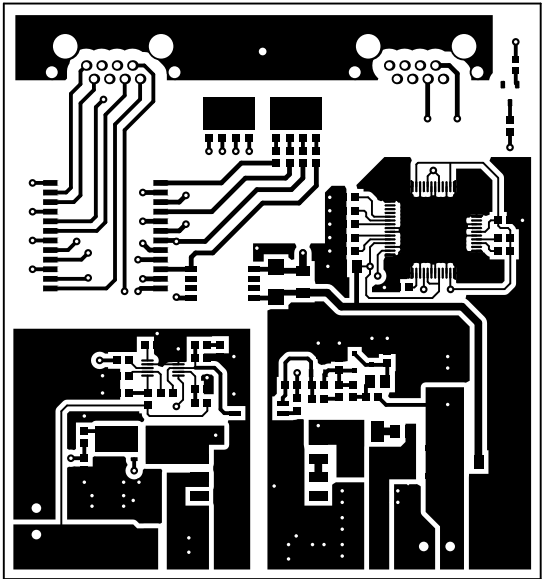




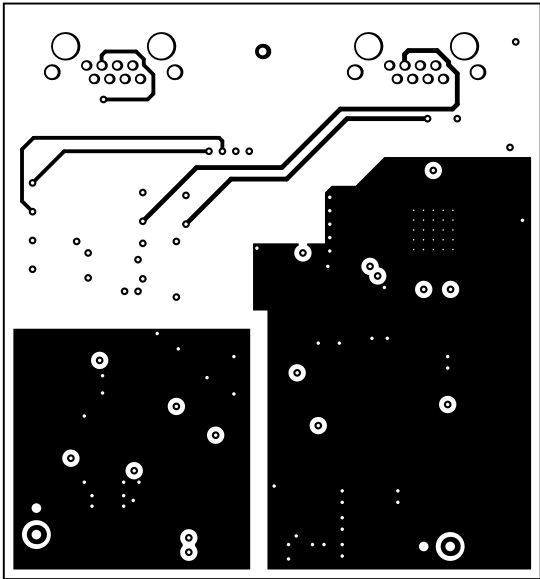
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20981	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 6/19/2017 5:06:30 PM	TEXAS INSTRUMENTS	



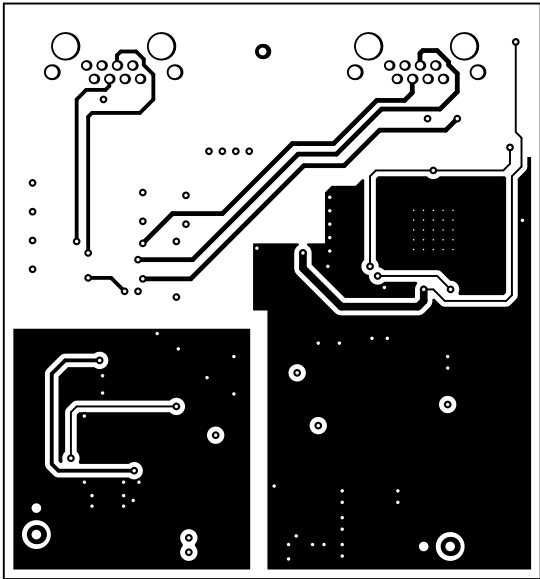
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20981	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 6/19/2017 5:06:31 PM		TEXAS INSTRUMENTS



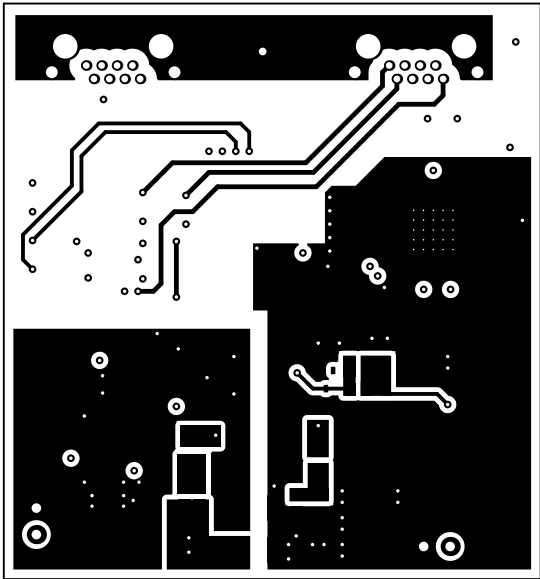
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20981	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 6/19/2017 5:06:32 PM		TEXAS INSTRUMENTS



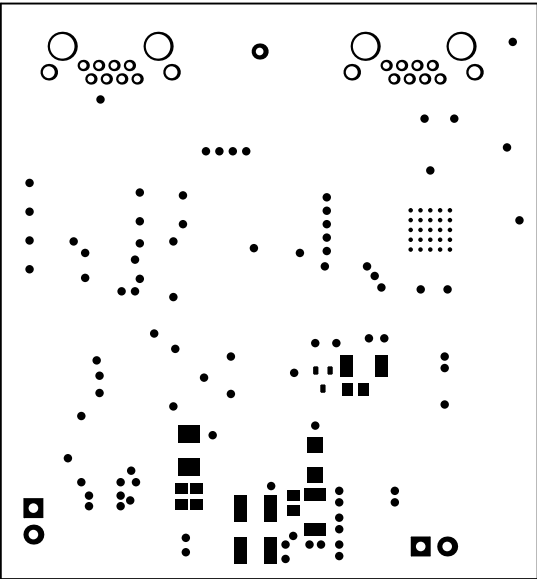
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20981	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 6/19/2017 5:06:32 PM		TEXAS INSTRUMENTS



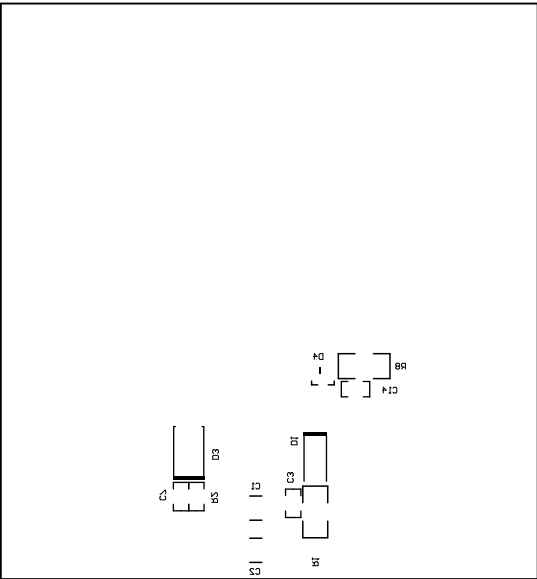
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20981	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 6/19/2017 5:06:33 PM		TEXAS INSTRUMENTS



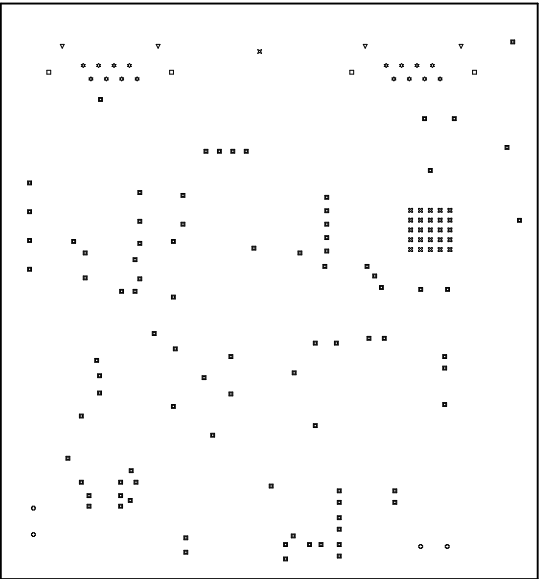
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20981	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 6/19/2017 5:06:34 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20981	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/19/2017 5:06:34 PM		TEXAS INSTRUMENTS

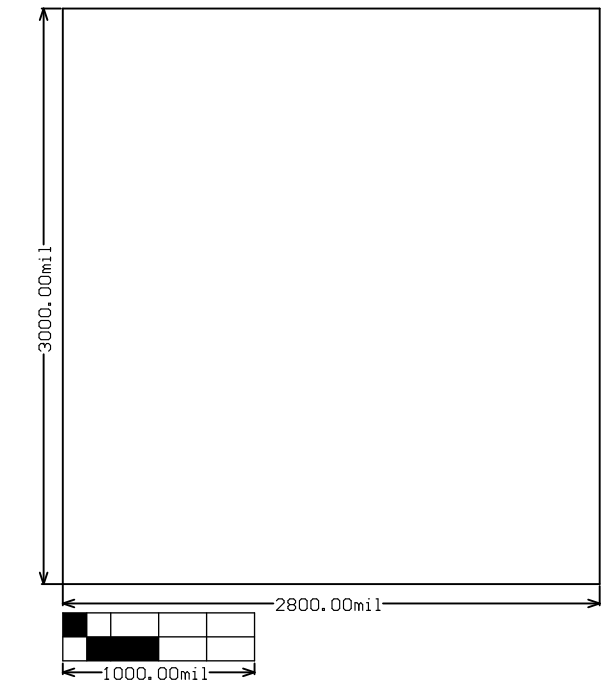


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20981	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 6/19/2017 5:06:35 PM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊠	25	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
■	88	18.00mil (0.457mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	16	35.04mil (0.890mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	1	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊚	4	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	61.81mil (1.570mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	128.00mil (3.251mm)	PTH	Round	Top Layer - Bottom Layer	
	142 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20981	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 6/19/2017 5:06:36 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	PMP20981	REV:	A	SUN REV:	Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:	N/A				
PLOT NAME = Board Dimensions	GENERATED	: 6/19/2017	5:06:37 PM	TEXAS INSTRUMENTS		

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